



Material Content Data Sheet



Sales Product Name				IPD135N03L G		Issued		27. September 2017	
MA#				MA000656390					
Package				PG-TO252-3-311		Weight*		316.26 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.562	0.18	0.18	1776	1776	
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		453		
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	copper	7440-50-8	143.098	45.25	45.31	452477	453066	
wire	non noble metal	aluminium	7429-90-5	0.832	0.26	0.26	2632	2632	
encapsulation	organic material	carbon black	1333-86-4	0.325	0.10		1027		
	plastics	epoxy resin	-	19.613	6.20		62016		
	inorganic material	silicondioxide	60676-86-0	127.750	40.39	46.69	403948	466991	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11826	11826	
plating	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	273	274	
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
solder	noble metal	silver	7440-22-4	0.021	0.01		68		
	non noble metal	tin	7440-31-5	0.017	0.01		54		
	non noble metal	lead	7439-92-1	0.821	0.26	0.28	2595	2717	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.06	6.07	60639	60718	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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